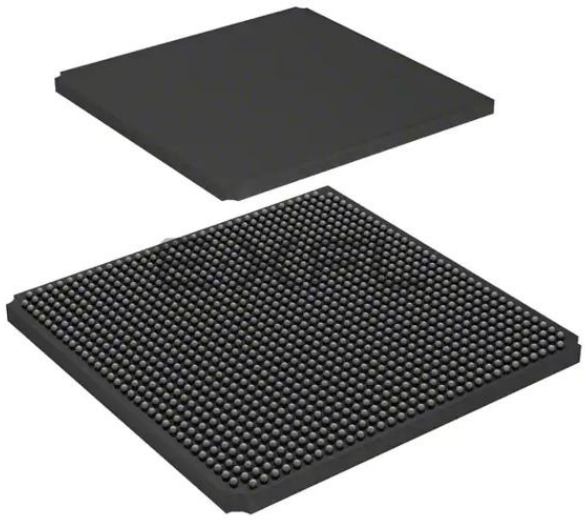
Lattice Semiconductor Corporation - LFSC3GA80E-7FC1152C Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	20000
Number of Logic Elements/Cells	80000
Total RAM Bits	5816320
Number of I/O	660
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BCBGA, FCBGA
Supplier Device Package	1152-CFCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfsc3ga80e-7fc1152c

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR 16x2 x 4 DPR 16x2 x 2	ROM 16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR 16x4 x 2 DPR 16x4 x 1	ROM 16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR 16x8 x 1	ROM 16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM 16x8 x1

Routing

There are many resources provided in the LatticeSC devices to route signals individually or as busses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

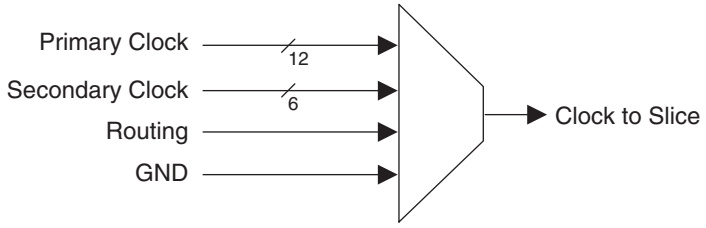
The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU) resources. The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. All connections are buffered to ensure high-speed operation even with long high-fanout connections.

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

sysCLOCK Network

The LatticeSC devices have three distinct clock networks for use in distributing high-performance clocks within the device: primary clocks, secondary clocks and edge clocks. In addition to these dedicated clock networks, users are free to route clocks within the device using the general purpose routing. Figure 2-4 shows the clock resources available to each slice.

Figure 2-4. Slice Clock Selection



Note: GND is available to switch off the network.

Primary Clock Sources

LatticeSC devices have a wide variety of primary clock sources available. Primary clocks sources consists of the following:

- Primary clock input pins
- Edge clock input pins
- Two outputs per DLL

Table 2-5. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
True Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18
Pseudo Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
FIFO	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Single, Dual and Pseudo-Dual Port Modes

In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output. A clock is required even in asynchronous read mode.

The EBR memory supports two forms of write behavior for dual port operation:

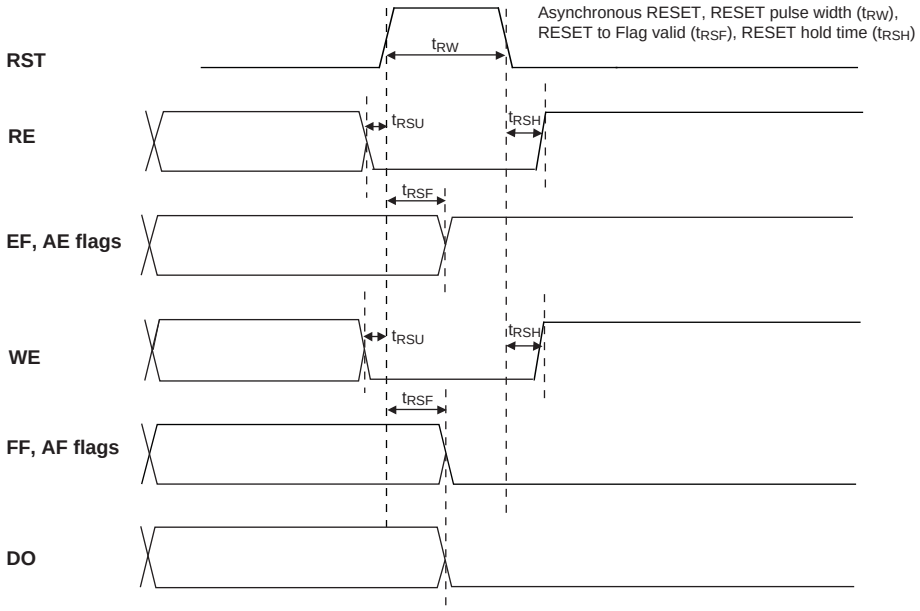
1. **Normal** — data on the output appears only during a read cycle. During a write cycle, the data (at the current address) does not appear on the output.

2. **Write Through** — a copy of the input data appears at the output of the same port.

FIFO Configuration

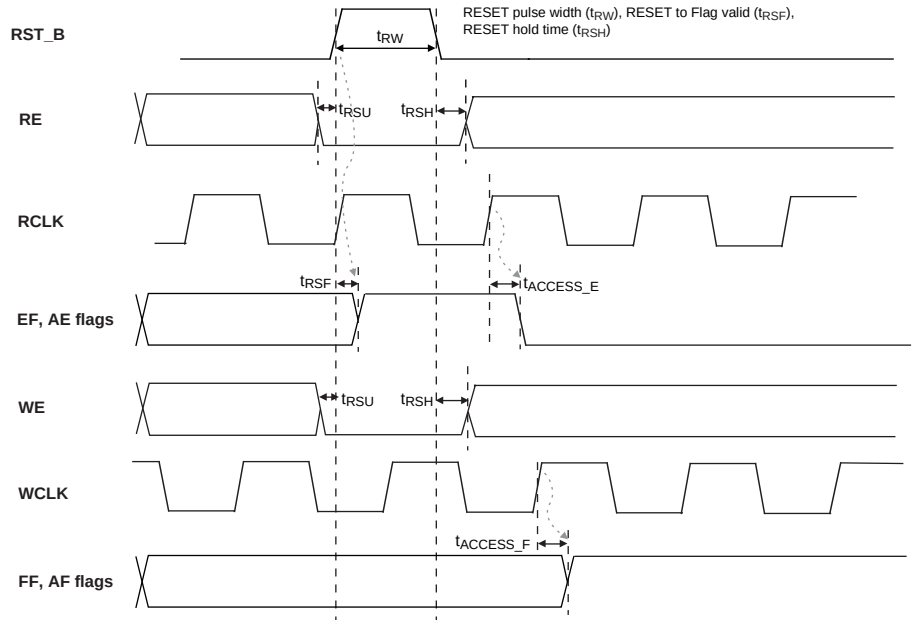
The FIFO has a write port with Data-in, WCE, WE and WCLK signals. There is a separate read port with Data-out, RCE, RE and RCLK signals. The FIFO internally generates Almost Full, Full, Almost Empty, and Empty Flags. The Full and Almost Full flags are registered with WCLK. The Empty and Almost Empty flags are registered with RCLK.

Figure 3-10. FIFO Reset Waveform



Note: RE and WE must be deactivated t_{RSU} before the Positive FIFO reset edge and enabled t_{RSH} after the FIFO reset negative edge.

Figure 3-11. Read Pointer Reset Waveform



Note: RE and WE must be deactivated t_{RSU} before the Positive FIFO reset edge and enabled t_{RSH} after the FIFO reset negative edge.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
RESETN		Reset. (Also sent to general routing). During configuration it resets the configuration state machine. After configuration this pin can perform the global set/reset (GSR) functions or can be used as a general input pin.
CFGIRQN	O	MPI Interrupt request active low signal is controlled by system bus interrupt controller and may be sourced from any bus error or MPI configuration error. It can be connected to one of MPC860 IRQ pins.
TSALLN	I	Tristates all I/O.
Configuration Pads (User I/O if not used. Used during sysCONFIG.)		
HDC/SI	O	High During Configuration is output high until configuration is complete. It is used as a control output, indicating that configuration is not complete. For SPI modes, this pin is used to download the read command and initial read address into the Flash memory device on the falling edge of SCK. This pin will be connected to SI of the memory. If the SPI mode is used, the 8-bit instruction code 0x03 will be downloaded followed by a 24-bit starting address of 0x000000 or a non-zero stat address for partial reconfiguration. If the SPIX mode has been selected, the 8-bit instruction captured on D[7:0] at power-up will be shifted in and followed by a 32-bit starting address of 0x000000.
LDCN/SCS	O	Low During Configuration is output low until configuration is complete. It is used as a control output, indicating that configuration is not complete. For SPI modes, this is an active low chip select for Flash memories. It will go active after INITN goes high but before SCK begins. During power up LDCN will be low. Once INITN goes high, LDCN will go high for 100ns-200ns after which time it will go back low and configuration can begin. During the 100ns-200ns period, the read instruction will be latched for SPIX mode.
DOUT	O	Serial data output that can drive the D0/DIN of daisy-chained slave devices. The data-stream from this output will propagate preamble bits of the bitstream to daisy-chained devices. Data out on DOUT changes on the rising edge of CCLK.
QOUT/CEON	O	During daisy-chaining configuration, QOUT is the serial data output that can drive the D0/DIN of daisy-chained slave devices that do not propagate preamble bits. Data out on QOUT changes on the rising edge of CCLK. During parallel-chaining configuration, active low CEON enables the cascaded slave device to receive bitstream data.
RDN	I	Used in the asynchronous peripheral configuration mode. A low on RDN changes D[7:3] into status outputs. WRN and RDN should not be used simultaneously. If they are, the write strobe overrides.
WRN	I	When the FPGA is selected, a low on the write strobe, WRN, loads the data on D[7:0] inputs into an internal data buffer.
CS0N CS1	I	Used in the asynchronous peripheral, slave parallel and MPI modes. The FPGA is selected when CS0N is low and CS1 is high. During configuration, a pull-up is enabled on both except with MPI DMA access control.
A[21:0]	I/O	In master parallel mode, A[21:0] is an output and will address the configuration EPROMs up to 4 MB space. For MPI configuration mode, A[17:0] will be the MPI address MPI_ADDR[31:14], A[19:18] will be the transfer size and A[21:20] will be the burst mode and burst in process.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
MPI_STRBN	I	Driven active low indicates the start of a transaction on the PowerPC bus. MPI will strobe the address bus at next rising edge of clock.
MPI_ADDR[31:14]	I	Address bus driven by a PowerPC bus master. Only 18-bit width is needed. It has to be the least significant bit of the PowerPC 32-bit address A[31:14].
MPI_DAT[n:0]	I/O	Selectable data bus width from 8, and 16-bit. Driven by a bus master in a write transaction. Driven by MPI in a read transaction.
MPI_PAR[m:0]	I/O	Selectable parity bus width from 1, 2, and 3-bit. MPI_DP[0] for MPI_D[7:0], MPI_DP[1] for MPI_D[15:8] and MPI_DP[2] for MPI_D[23:16].
MPI_TA	O	Transfer acknowledge. Driven active low indicates that MPI received the data on the write cycle or returned data on the read cycle.
MPI_TEA	O	Transfer Error Acknowledge. Driven active low indicates that MPI detects a bus error on the internal system bus for current transaction.
MPI_RETRY	O	Active low MPI Retry requests the MPC860 to relinquish the bus and retry the cycle.
Multi-chip Alignment (User I/O if not used.)		
MCA_DONE_OUT	O	Multi-chip alignment done output (to second MCA chip)
MCA_DONE_IN	I	Multi-chip alignment done input (from second MCA chip)
MCA_CLK_P[1:2]_OUT	O	Multi-chip alignment clock [1:2] output (sourced by MCA master chip)
MCA_CLK_P[1:2]_IN	I	Multi-chip alignment clock [1:2] input (from MCA master chip
TEMP	—	Temperature sensing diode pin. Dedicated pin. Accuracy is typically +/- 10°C.
Miscellaneous Dedicated Pins		
XRES	—	External reference resistor between this pin and ground. The reference resistor is used to calibrate the programmable terminating resistors used in the I/Os. Dedicated pin. Value: 1K ± 1% ohm.
DIFFRx	—	Only used if a differential driver is used in a bank. This DIFFRx must be connected to ground via an external 1K ±1% ohm resistor for all banks that have a differential driver.
SERDES Block (Dedicated Pins)		
[A:D]_HDINPx_[L/R]	I	High-speed input (positive) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDINNx_[L/R]	I	High-speed input (negative) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDOUTPx_[L/R]	O	High-speed output (positive) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDOUTNx_[L/R]	O	High-speed output (negative) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_REFCLKP_[L/R]	I	Ref clock input (positive), aux channel on left [L] or right [R] side of device.
[A:D]_REFCLKN_[L/R]	I	Ref clock input (negative), aux channel on left [L] or right [R] side of device.

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
A29	RESP_URC	-		RESP_URC	-	
D26	VCC12	-		VCC12	-	
C30	A_REFCLKN_R	-		A_REFCLKN_R	-	
B30	A_REFCLKP_R	-		A_REFCLKP_R	-	
F24	A_VDDAX25_R	-		A_VDDAX25_R	-	
D25	VCC12	-		VCC12	-	
C28	A_VDDIB0_R	-		A_VDDIB0_R	-	
B28	A_HDINP0_R	-	PCS 3E0 CH 0 IN P	A_HDINP0_R	-	PCS 3E0 CH 0 IN P
B27	A_HDINN0_R	-	PCS 3E0 CH 0 IN N	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
E25	VCC12	-		VCC12	-	
A28	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P
C27	A_VDDOB0_R	-		A_VDDOB0_R	-	
A27	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
C26	A_VDDOB1_R	-		A_VDDOB1_R	-	
A26	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
D24	VCC12	-		VCC12	-	
A25	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
B26	A_HDINN1_R	-	PCS 3E0 CH 1 IN N	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
B25	A_HDINP1_R	-	PCS 3E0 CH 1 IN P	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
E24	VCC12	-		VCC12	-	
C25	A_VDDIB1_R	-		A_VDDIB1_R	-	
D23	VCC12	-		VCC12	-	
C24	A_VDDIB2_R	-		A_VDDIB2_R	-	
B24	A_HDINP2_R	-	PCS 3E0 CH 2 IN P	A_HDINP2_R	-	PCS 3E0 CH 2 IN P
B23	A_HDINN2_R	-	PCS 3E0 CH 2 IN N	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
E23	VCC12	-		VCC12	-	
A24	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
C23	A_VDDOB2_R	-		A_VDDOB2_R	-	
A23	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
C22	A_VDDOB3_R	-		A_VDDOB3_R	-	
A22	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
D22	VCC12	-		VCC12	-	
A21	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
B22	A_HDINN3_R	-	PCS 3E0 CH 3 IN N	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
B21	A_HDINP3_R	-	PCS 3E0 CH 3 IN P	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
E22	VCC12	-		VCC12	-	
C21	A_VDDIB3_R	-		A_VDDIB3_R	-	
G22	PT43D	1	HDC/SI	PT49D	1	HDC/SI
F22	PT43C	1	LDCN/SCS	PT49C	1	LDCN/SCS
B20	PT41B	1	D8/MPI_DATA8	PT49B	1	D8/MPI_DATA8
B19	PT41A	1	CS1/MPI_CS1	PT49A	1	CS1/MPI_CS1
A20	PT40D	1	D9/MPI_DATA9	PT47D	1	D9/MPI_DATA9
A19	PT40C	1	D10/MPI_DATA10	PT47C	1	D10/MPI_DATA10
D19	PT39B	1	CS0N/MPI_CS0N	PT47B	1	CS0N/MPI_CS0N
D18	PT39A	1	RDN/MPI_STRB_N	PT47A	1	RDN/MPI_STRB_N

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
F19	PT24A	1	MPI_TEA	PT30A	1	MPI_TEA
J18	PT23D	1	D14/MPI_DATA14	PT28D	1	D14/MPI_DATA14
K18	PT23C	1	DP1/MPI_PAR1	PT28C	1	DP1/MPI_PAR1
E20	PT23B	1	A21/MPI_BURST	PT27B	1	A21/MPI_BURST
F20	PT23A	1	D15/MPI_DATA15	PT27A	1	D15/MPI_DATA15
C23	B_REFCLKP_L	-		B_REFCLKP_L	-	
D23	B_REFCLKN_L	-		B_REFCLKN_L	-	
B23	VCC12	-		VCC12	-	
H21	B_VDDIB3_L	-		B_VDDIB3_L	-	
F21	B_HDINP3_L	-	PCS 361 CH 3 IN P	B_HDINP3_L	-	PCS 361 CH 3 IN P
G21	B_HDINN3_L	-	PCS 361 CH 3 IN N	B_HDINN3_L	-	PCS 361 CH 3 IN N
A21	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P
B21	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N
D21	B_VDDOB3_L	-		B_VDDOB3_L	-	
B22	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N
D22	B_VDDOB2_L	-		B_VDDOB2_L	-	
A22	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P
G22	B_HDINN2_L	-	PCS 361 CH 2 IN N	B_HDINN2_L	-	PCS 361 CH 2 IN N
F22	B_HDINP2_L	-	PCS 361 CH 2 IN P	B_HDINP2_L	-	PCS 361 CH 2 IN P
H22	B_VDDIB2_L	-		B_VDDIB2_L	-	
H24	B_VDDIB1_L	-		B_VDDIB1_L	-	
G23	B_HDINP1_L	-	PCS 361 CH 1 IN P	B_HDINP1_L	-	PCS 361 CH 1 IN P
H23	B_HDINN1_L	-	PCS 361 CH 1 IN N	B_HDINN1_L	-	PCS 361 CH 1 IN N
A24	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P
B24	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N
D24	B_VDDOB1_L	-		B_VDDOB1_L	-	
B25	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N
D25	B_VDDOB0_L	-		B_VDDOB0_L	-	
A25	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P
G25	B_HDINN0_L	-	PCS 361 CH 0 IN N	B_HDINN0_L	-	PCS 361 CH 0 IN N
F25	B_HDINP0_L	-	PCS 361 CH 0 IN P	B_HDINP0_L	-	PCS 361 CH 0 IN P
H25	B_VDDIB0_L	-		B_VDDIB0_L	-	
H26	A_VDDIB3_L	-		A_VDDIB3_L	-	
F26	A_HDINP3_L	-	PCS 360 CH 3 IN P	A_HDINP3_L	-	PCS 360 CH 3 IN P
G26	A_HDINN3_L	-	PCS 360 CH 3 IN N	A_HDINN3_L	-	PCS 360 CH 3 IN N
A26	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
B26	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
D26	A_VDDOB3_L	-		A_VDDOB3_L	-	
B27	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
D27	A_VDDOB2_L	-		A_VDDOB2_L	-	
A27	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
G27	A_HDINN2_L	-	PCS 360 CH 2 IN N	A_HDINN2_L	-	PCS 360 CH 2 IN N
F27	A_HDINP2_L	-	PCS 360 CH 2 IN P	A_HDINP2_L	-	PCS 360 CH 2 IN P
H27	A_VDDIB2_L	-		A_VDDIB2_L	-	
F29	A_VDDIB1_L	-		A_VDDIB1_L	-	
G28	A_HDINP1_L	-	PCS 360 CH 1 IN P	A_HDINP1_L	-	PCS 360 CH 1 IN P
H28	A_HDINN1_L	-	PCS 360 CH 1 IN N	A_HDINN1_L	-	PCS 360 CH 1 IN N
A29	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
B29	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
D29	A_VDDOB1_L	-		A_VDDOB1_L	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
E22	VCC12	-		VCC12	-	
E21	VCC12	-		VCC12	-	
E3	VCC12	-		VCC12	-	
E4	VCC12	-		VCC12	-	
E6	VCC12	-		VCC12	-	
E7	VCC12	-		VCC12	-	
E8	VCC12	-		VCC12	-	
E9	VCC12	-		VCC12	-	
E11	VCC12	-		VCC12	-	
E12	VCC12	-		VCC12	-	
A23	GND	-		GND	-	
A31	GND	-		GND	-	
AA13	GND	-		GND	-	
AA15	GND	-		GND	-	
AA18	GND	-		GND	-	
AA20	GND	-		GND	-	
AA26	GND	-		GND	-	
AA6	GND	-		GND	-	
AB10	GND	-		GND	-	
AB24	GND	-		GND	-	
AC14	GND	-		GND	-	
AC22	GND	-		GND	-	
AC29	GND	-		GND	-	
AC3	GND	-		GND	-	
AD11	GND	-		GND	-	
AD19	GND	-		GND	-	
AD27	GND	-		GND	-	
AD7	GND	-		GND	-	
AF12	GND	-		GND	-	
AF18	GND	-		GND	-	
AF24	GND	-		GND	-	
AF30	GND	-		GND	-	
AF4	GND	-		GND	-	
AG15	GND	-		GND	-	
AG21	GND	-		GND	-	
AG9	GND	-		GND	-	
AJ10	GND	-		GND	-	
AJ16	GND	-		GND	-	
AJ20	GND	-		GND	-	
AJ26	GND	-		GND	-	
AJ29	GND	-		GND	-	
AJ4	GND	-		GND	-	
AK13	GND	-		GND	-	
AK17	GND	-		GND	-	
AK23	GND	-		GND	-	
AK7	GND	-		GND	-	
AL1	GND	-		GND	-	
AL32	GND	-		GND	-	
AM2	GND	-		GND	-	
AM31	GND	-		GND	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
P10	GND	-		GND	-	
P13	GND	-		GND	-	
P15	GND	-		GND	-	
P18	GND	-		GND	-	
P20	GND	-		GND	-	
P24	GND	-		GND	-	
R12	GND	-		GND	-	
R14	GND	-		GND	-	
R16	GND	-		GND	-	
R17	GND	-		GND	-	
R19	GND	-		GND	-	
R21	GND	-		GND	-	
R26	GND	-		GND	-	
R6	GND	-		GND	-	
T15	GND	-		GND	-	
T18	GND	-		GND	-	
T30	GND	-		GND	-	
T4	GND	-		GND	-	
U15	GND	-		GND	-	
U18	GND	-		GND	-	
U29	GND	-		GND	-	
U3	GND	-		GND	-	
V12	GND	-		GND	-	
V14	GND	-		GND	-	
V16	GND	-		GND	-	
V17	GND	-		GND	-	
V19	GND	-		GND	-	
V21	GND	-		GND	-	
V27	GND	-		GND	-	
V7	GND	-		GND	-	
W13	GND	-		GND	-	
W15	GND	-		GND	-	
W18	GND	-		GND	-	
W20	GND	-		GND	-	
W23	GND	-		GND	-	
W9	GND	-		GND	-	
Y12	GND	-		GND	-	
Y14	GND	-		GND	-	
Y19	GND	-		GND	-	
Y21	GND	-		GND	-	
Y30	GND	-		GND	-	
Y4	GND	-		GND	-	
N13	VCC	-		VCC	-	
N15	VCC	-		VCC	-	
N16	VCC	-		VCC	-	
N17	VCC	-		VCC	-	
N18	VCC	-		VCC	-	
N20	VCC	-		VCC	-	
P14	VCC	-		VCC	-	
P16	VCC	-		VCC	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AD29	PL60D	6		PL84D	6	
AE31	PL61A	6		PL85A	6	
AF31	PL61B	6		PL85B	6	
AF30	PL61C	6		PL85C	6	
AF29	PL61D	6		PL85D	6	
AH33	PL62A	6		PL86A	6	
AJ33	PL62B	6		PL86B	6	
AC28	PL62C	6		PL86C	6	
AD28	PL62D	6		PL86D	6	
AH32	PL65A	6		PL89A	6	
AJ32	PL65B	6		PL89B	6	
AD27	PL65C	6		PL89C	6	
AE27	PL65D	6	VREF2_6	PL89D	6	VREF2_6
AG34	PL66A	6		PL90A	6	
AH34	PL66B	6		PL90B	6	
AC26	PL66C	6		PL90C	6	
AB26	PL66D	6		PL90D	6	
AK33	PL67A	6		PL91A	6	
AL33	PL67B	6		PL91B	6	
AG30	PL67C	6		PL91C	6	
AH30	PL67D	6		PL91D	6	
AL34	PL69A	6		PL93A	6	
AM34	PL69B	6		PL93B	6	
AJ30	PL69C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F	PL93C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F
AK30	PL69D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F	PL93D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F
AJ31	PL70A	6		PL94A	6	
AH31	PL70B	6		PL94B	6	
AD26	PL70C	6		PL94C	6	
AD25	PL70D	6		PL94D	6	
AL32	PL71A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E	PL95A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
AL31	PL71B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E	PL95B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E
AG29	PL71C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A	PL95C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A
AG28	PL71D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A	PL95D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A
AF28	XRES	-		XRES	-	
AF27	TEMP	6		TEMP	6	
AM33	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B
AN33	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B
AH29	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D
AJ29	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D
AM32	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C
AM31	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C
AG27	PB4C	5		PB4C	5	
AG26	PB4D	5		PB4D	5	
AL29	PB5A	5		PB5A	5	
AL28	PB5B	5		PB5B	5	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
Y4	PR48B	3		PR63B	3	
W4	PR48A	3		PR63A	3	
W11	PR47D	3		PR60D	3	
V11	PR47C	3		PR60C	3	
W2	PR47B	3		PR60B	3	
V2	PR47A	3		PR60A	3	
W9	PR45D	3		PR57D	3	
V9	PR45C	3		PR57C	3	
V1	PR45B	3		PR57B	3	
U1	PR45A	3		PR57A	3	
W10	PR44D	3		PR56D	3	
V10	PR44C	3		PR56C	3	
U2	PR44B	3		PR56B	3	
T2	PR44A	3		PR56A	3	
Y8	PR43D	3		PR55D	3	
W8	PR43C	3	VREF1_3	PR55C	3	VREF1_3
W5	PR43B	3		PR55B	3	
V5	PR43A	3		PR55A	3	
V7	PR40D	3	PCLKC3_2	PR52D	3	PCLKC3_2
U7	PR40C	3	PCLKT3_2	PR52C	3	PCLKT3_2
T1	PR40B	3		PR52B	3	
R1	PR40A	3		PR52A	3	
V8	PR39D	3	PCLKC3_3	PR51D	3	PCLKC3_3
U8	PR39C	3	PCLKT3_3	PR51C	3	PCLKT3_3
U5	PR39B	3		PR51B	3	
T5	PR39A	3		PR51A	3	
V6	PR38D	3	PCLKC3_1	PR50D	3	PCLKC3_1
U6	PR38C	3	PCLKT3_1	PR50C	3	PCLKT3_1
T4	PR38B	3	PCLKC3_0	PR50B	3	PCLKC3_0
T3	PR38A	3	PCLKT3_0	PR50A	3	PCLKT3_0
U9	PR36D	2	PCLKC2_2	PR48D	2	PCLKC2_2
T9	PR36C	2	PCLKT2_2	PR48C	2	PCLKT2_2
R2	PR36B	2	PCLKC2_0	PR48B	2	PCLKC2_0
P2	PR36A	2	PCLKT2_0	PR48A	2	PCLKT2_0
T11	PR35D	2	PCLKC2_3	PR47D	2	PCLKC2_3
U11	PR35C	2	PCLKT2_3	PR47C	2	PCLKT2_3
R4	PR35B	2	PCLKC2_1	PR47B	2	PCLKC2_1
R3	PR35A	2	PCLKT2_1	PR47A	2	PCLKT2_1
T8	PR34D	2		PR46D	2	
R8	PR34C	2		PR46C	2	
P1	PR34B	2		PR46B	2	
N1	PR34A	2		PR46A	2	
R6	PR31D	2		PR43D	2	
P6	PR31C	2		PR43C	2	
M1	PR31B	2		PR43B	2	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
L1	PR31A	2		PR43A	2	
T10	PR30D	2		PR42D	2	
U10	PR30C	2		PR42C	2	
N2	PR30B	2		PR42B	2	
M2	PR30A	2		PR42A	2	
R11	PR29D	2		PR37D	2	
P11	PR29C	2		PR37C	2	
N4	PR29B	2		PR37B	2	
M4	PR29A	2		PR37A	2	
N5	PR27D	2		PR35D	2	
M5	PR27C	2		PR35C	2	
L2	PR27B	2		PR35B	2	
K2	PR27A	2		PR35A	2	
P8	PR26D	2		PR33D	2	
N8	PR26C	2		PR33C	2	
J2	PR26B	2		PR33B	2	
H2	PR26A	2		PR33A	2	
M6	PR25D	2		PR31D	2	
L6	PR25C	2		PR31C	2	
K3	PR25B	2		PR31B	2	
J3	PR25A	2		PR31A	2	
M8	PR23D	2	DIFFR_2	PR29D	2	DIFFR_2
L8	PR23C	2	VREF1_2	PR29C	2	VREF1_2
K4	PR23B	2		PR29B	2	
J4	PR23A	2		PR29A	2	
M7	PR22D	2		PR21D	2	
L7	PR22C	2		PR21C	2	
J5	PR22B	2		PR21B	2	
H5	PR22A	2		PR21A	2	
N9	PR21D	2		PR20D	2	
P9	PR21C	2		PR20C	2	
G3	PR21B	2		PR20B	2	
F3	PR21A	2		PR20A	2	
J6	PR18D	2	VREF2_2	PR18D	2	VREF2_2
H6	PR18C	2		PR18C	2	
E2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
D2	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
P10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
N10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
G4	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
F4	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
J7	PR16D	2		PR16D	2	
H7	PR16C	2		PR16C	2	
G5	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
F5	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AF40	PL76A	6		PL90A	6	
AG40	PL76B	6		PL90B	6	
AG36	PL76C	6		PL90C	6	
AH36	PL76D	6	DIFFR_6	PL90D	6	DIFFR_6
AF39	PL77A	6		PL91A	6	
AG39	PL77B	6		PL91B	6	
AF29	PL77C	6		PL91C	6	
AG29	PL77D	6		PL91D	6	
AH42	PL78A	6		PL92A	6	
AG42	PL78B	6		PL92B	6	
AG35	PL78C	6		PL92C	6	
AH35	PL78D	6		PL92D	6	
AG41	PL80A	6		PL94A	6	
AH41	PL80B	6		PL94B	6	
AG34	PL80C	6		PL94C	6	
AH34	PL80D	6		PL94D	6	
AJ42	PL81A	6		PL96A	6	
AK42	PL81B	6		PL96B	6	
AG33	PL81C	6		PL96C	6	
AH33	PL81D	6		PL96D	6	
AJ41	PL82A	6		PL98A	6	
AK41	PL82B	6		PL98B	6	
AJ37	PL82C	6		PL98C	6	
AK37	PL82D	6		PL98D	6	
AJ40	PL84A	6		PL99A	6	
AK40	PL84B	6		PL99B	6	
AJ34	PL84C	6		PL99C	6	
AK34	PL84D	6		PL99D	6	
AJ38	PL85A	6		PL103A	6	
AK38	PL85B	6		PL103B	6	
AH32	PL85C	6		PL103C	6	
AJ32	PL85D	6		PL103D	6	
AL42	PL86A	6		PL104A	6	
AM42	PL86B	6		PL104B	6	
AK36	PL86C	6		PL104C	6	
AL36	PL86D	6		PL104D	6	
AL38	PL89A	6		PL107A	6	
AM38	PL89B	6		PL107B	6	
AJ33	PL89C	6		PL107C	6	
AK33	PL89D	6	VREF2_6	PL107D	6	VREF2_6
AN42	PL90A	6		PL109A	6	
AP42	PL90B	6		PL109B	6	
AH31	PL90C	6		PL109C	6	
AJ31	PL90D	6		PL109D	6	
AN41	PL91A	6		PL112A	6	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AC24	GND	-		GND	-	
AC26	GND	-		GND	-	
AC35	GND	-		GND	-	
AC8	GND	-		GND	-	
AD12	GND	-		GND	-	
AD16	GND	-		GND	-	
AD18	GND	-		GND	-	
AD20	GND	-		GND	-	
AD23	GND	-		GND	-	
AD25	GND	-		GND	-	
AD27	GND	-		GND	-	
AD31	GND	-		GND	-	
AE17	GND	-		GND	-	
AE19	GND	-		GND	-	
AE24	GND	-		GND	-	
AE26	GND	-		GND	-	
AE3	GND	-		GND	-	
AE39	GND	-		GND	-	
AF18	GND	-		GND	-	
AF20	GND	-		GND	-	
AF23	GND	-		GND	-	
AF25	GND	-		GND	-	
AF36	GND	-		GND	-	
AF7	GND	-		GND	-	
AG11	GND	-		GND	-	
AG16	GND	-		GND	-	
AG19	GND	-		GND	-	
AG24	GND	-		GND	-	
AG27	GND	-		GND	-	
AG32	GND	-		GND	-	
AH15	GND	-		GND	-	
AH28	GND	-		GND	-	
AH4	GND	-		GND	-	
AH40	GND	-		GND	-	
AJ35	GND	-		GND	-	
AJ8	GND	-		GND	-	
AK12	GND	-		GND	-	
AK31	GND	-		GND	-	
AL13	GND	-		GND	-	
AL19	GND	-		GND	-	
AL24	GND	-		GND	-	
AL3	GND	-		GND	-	
AL30	GND	-		GND	-	
AL39	GND	-		GND	-	
AM16	GND	-		GND	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
C3	GND	-		GND	-	
C30	GND	-		GND	-	
C33	GND	-		GND	-	
C35	GND	-		GND	-	
C36	GND	-		GND	-	
C39	GND	-		GND	-	
C4	GND	-		GND	-	
C40	GND	-		GND	-	
C7	GND	-		GND	-	
C8	GND	-		GND	-	
D15	GND	-		GND	-	
D21	GND	-		GND	-	
D25	GND	-		GND	-	
D31	GND	-		GND	-	
F4	GND	-		GND	-	
F40	GND	-		GND	-	
G11	GND	-		GND	-	
G17	GND	-		GND	-	
G26	GND	-		GND	-	
G32	GND	-		GND	-	
H14	GND	-		GND	-	
H20	GND	-		GND	-	
H23	GND	-		GND	-	
H29	GND	-		GND	-	
H35	GND	-		GND	-	
H8	GND	-		GND	-	
J3	GND	-		GND	-	
J39	GND	-		GND	-	
L16	GND	-		GND	-	
L27	GND	-		GND	-	
L36	GND	-		GND	-	
L7	GND	-		GND	-	
M19	GND	-		GND	-	
M24	GND	-		GND	-	
M4	GND	-		GND	-	
M40	GND	-		GND	-	
N12	GND	-		GND	-	
N31	GND	-		GND	-	
P35	GND	-		GND	-	
P8	GND	-		GND	-	
R15	GND	-		GND	-	
R28	GND	-		GND	-	
R3	GND	-		GND	-	
R39	GND	-		GND	-	
T11	GND	-		GND	-	

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1101 - Power Estimation and Management for LatticeSC Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

Conventional Packaging

Commercial

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA15E-7F256C	-7	fpBGA	256	COM	15.2
LFSC3GA15E-6F256C	-6	fpBGA	256	COM	15.2
LFSC3GA15E-5F256C	-5	fpBGA	256	COM	15.2
LFSC3GA15E-7F900C	-7	fpBGA	900	COM	15.2
LFSC3GA15E-6F900C	-6	fpBGA	900	COM	15.2
LFSC3GA15E-5F900C	-5	fpBGA	900	COM	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA15EP1-7F256C	-7	fpBGA	256	COM	15.2
LFSCM3GA15EP1-6F256C	-6	fpBGA	256	COM	15.2
LFSCM3GA15EP1-5F256C	-5	fpBGA	256	COM	15.2
LFSCM3GA15EP1-7F900C	-7	fpBGA	900	COM	15.2
LFSCM3GA15EP1-6F900C	-6	fpBGA	900	COM	15.2
LFSCM3GA15EP1-5F900C	-5	fpBGA	900	COM	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA25E-7F900C	-7	fpBGA	900	COM	25.4
LFSC3GA25E-6F900C	-6	fpBGA	900	COM	25.4
LFSC3GA25E-5F900C	-5	fpBGA	900	COM	25.4
LFSC3GA25E-7FF1020C[1]	-7	Organic fcBGA	1020	COM	25.4
LFSC3GA25E-6FF1020C[1]	-6	Organic fcBGA	1020	COM	25.4
LFSC3GA25E-5FF1020C[1]	-5	Organic fcBGA	1020	COM	25.4
LFSC3GA25E-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	25.4
LFSC3GA25E-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	25.4
LFSC3GA25E-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA25EP1-7F900C	-7	fpBGA	900	COM	25.4
LFSCM3GA25EP1-6F900C	-6	fpBGA	900	COM	25.4
LFSCM3GA25EP1-5F900C	-5	fpBGA	900	COM	25.4
LFSCM3GA25EP1-7FF1020C[1]	-7	Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-6FF1020C[1]	-6	Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-5FF1020C[1]	-5	Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	25.4
LFSCM3GA25EP1-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	25.4
LFSCM3GA25EP1-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

LatticeSC/M Family Data Sheet Supplemental Information

January 2008 **Data Sheet DS1004**

For Further Information

For further information about the flexiPCS, see the LatticeSC/M Family flexiPCS Data Sheet.

A variety of technical notes for the LatticeSC/M family are also available on the Lattice Semiconductor website at www.latticesemi.com.

- LatticeSC PURESPEED I/O Usage Guide (TN1088)
- LatticeSC PURESPEED I/O Adaptive Input Logic User's Guide (TN1158)
- LatticeSC sysCLOCK PLL/DLL User's Guide (TN1098)
- On-Chip Memory Usage Guide for LatticeSC Devices (TN1094)
- LatticeSC/M DDR/DDR2 SDRAM Memory Interface User's Guide (TN1099)
- LatticeSC QDRII/II+ SRAM Memory Interface User's Guide (TN1096)
- LatticeSC sysCONFIG Usage Guide (TN1080)
- LatticeSC MPI/System Bus (TN1085)
- SPI Serial Flash Programming Using ispJTAG in LatticeSC Devices (TN1100)
- Power Estimation and Management for LatticeSC Devices (TN1101)
- LatticeSC SERDES Jitter (TN1084)
- LatticeSC FPGAs: Implementing 3.3V Interfaces in 2.5V VCCIO Banks (TN1110)
- Lattice PCI Express Basic Demo User's Guide (UG08)
- LatticeSC flexiPCS/SERDES Design Guide (TN1145)
- Temperature Sensing Diode in LatticeSC Devices (TN1115)
- SPI4.2 Interoperability Between ORSPI4 and LatticeSC Devices (TN1116)

For further information on Interface standards refer to the following websites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- Optical Interface (SPI-4.2, XSBI, CSIX and XGMII): www.oiforum.com
- RAPIDIO: www.rapidio.org
- PCI/PCIX: ww.pcisig.com

Date	Version	Section	Change Summary
August 2006 (cont.)	01.3 (cont.)	DC and Switching Characteristics (cont.)	Updated LatticeSC Family Timing Adders with ispLEVER 6.0 SP1 results
			Updated PLL Timing Parameters based on PDE testing results
			Removed RDDATA parameter from sysCONFIG readback timing table
		Multiple	Changed TDO/RDDATA to TDO
		Pinout Information	Removed all MPI signals from SC15 256 pin package Dual Function Column
			Added note to SC15, SC25 900 pin package that the package supports a 16 bit MPI
			Added note that pin D3 in an SC15 and SC25 900 pin package should not be used for single-ended outputs
			Added note that pin D28 in an SC15 and SC25 900 pin package should not be used for single-ended outputs
			Added note to SC25 1020 pin package that the package supports a 16 bit MPI
			Added note to SC80 1152 pin package that the package supports a 32 bit MPI
			Added note to SC80 1704 pin package that the package supports a 32 bit MPI
		Ordering Information	Changed “fcBGA” for the 1020 packages to “ffBGA”
November 2006	01.4	Introduction	LatticeSC Family Selection Guide table – I/O count for SC80 device, 1704 fcBGA package changed to 904/32. I/O count for SC115 device, 1704 fcBGA package changed to 942/32.
		DC and Switching Characteristics	DC Electrical Characteristics table – Updated the initialization and standby supply current values.
			DC Electrical Characteristics table – Updated the sysCONFIG Master Parallel mode RCLK low and RCLK high time specifications.
			DC Electrical Characteristics table – Updated VCCIO values for LVPECL33 I/Os.
		Pin Information	Pin Information Summary table - Changed number of single ended user I/Os from 906 to 904 for 1704 fcBGA.
			Removed the single-ended only output restriction on pins D3 and D28 in an SC15 and SC25 900 pin package.
		Ordering Information	Ordering Information tables - Changed number of I/Os from 906 to 904 for 1704 fcBGA.
			Added ordering part numbers for LatticeSC/SCM 40K and 115K LUT devices.
			Added lead-free ordering part numbers.
		Multiple	Changed number of available SC80 I/O from 906 to 904.
			Changed number of available SC115 I/O from 944 to 942.
January 2007	01.4a	Architecture	Added EBR Asynchronous Reset section.
February 2007	01.4b	Architecture	Updated EBR Asynchronous Reset section.
March 2007	01.5	Architecture	Added EBR asynchronous reset clarification
			Clarified that differential drivers are not supported in banks 1, 4 and 5
		DC and Switching Characteristics	Added clarification for the description of the junction temperature specification in the Absolute Maximum Ratings section.
			Updated Initialization and Standby Current table.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.1 SP1 results.

Date	Version	Section	Change Summary
September 2007	01.7	Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.
November 2007	01.8	Ordering Information	Removed -7 speed grade information for 115K LUT devices in the Ordering Information tables.
January 2008	01.9	Introduction	Corrections/Additions to memory controller list (Tables 1-2).
		Architecture	AIL Overview – Modified power used by AIL block.
			PURESPEED I/O Buffer Banks – Modified VTT termination info. Added info about complimentary drivers for all banks.
			Supported Source Synchronous Interfaces – Modified data for DDRII in Table 2-11.
		DC and Switching Characteristics	Recommended Operating Conditions – Changed footnote 3.
			Initialization and Standby Supply Current – Inserted a paragraph with info regarding the table. Also updated the table.
			Typical Building Block Function Performance – Added VCC=1.2V=1.2V+/-5% above Pin to Pin Performance table.
			LatticeSC External Switching Characteristics – Added VCC=1.2V=1.2V+/-5% above table. Reworded footnote 3.
			LatticeSC Family Timing Adders – Added VCC=1.2V=1.2V+/-5% above table.
			LatticeSC Internal Timing Parameters – Added VCC=1.2V=1.2V+/-5% above table. Reworded footnote 1.
			GSR Timing – Added a new table for Internal System Bus Timing after GSR Timing.
			LatticeSC sysCONFIG Port Timing – Corrected sysCONFIG SPI Port information.
		Pinout Information	Signal Descriptions – Modified info for VTT_x, PROBE_VCC, and PROBE_GND. Modified info for [LOC]_DLL[T,C]_IN[C,D,E,F].
		Supplemental Information	Updated list of technical notes, added reference to LatticeSC/M flexiPCS Data Sheet.
March 2008	02.0	DC and Switching Characteristics	Updated Internal Timing Parameters table.
			Updated Read Mode timing diagram.
			Updated Read Mode with Input Registers Only timing diagram.
June 2008	02.1	—	Data sheet status changed from preliminary to final.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
		DC and Switching Characteristics	Updated LatticeSC/M External Switching Characteristics table.
			Updated LatticeSC/M Internal Timing Parameters table.
			Removed Read-Before-Write sysMEM EBR mode.
December 2008	02.2	Architecture	Output/Tristate DDR/Shift Register Block Diagram - corrected connection to POS.
		DC and Switching Characteristics	DC and Switching Characteristics table - updated data for $t_{SUI\_PIO.}$
			Added $T_{R,}$ T_F parameter to PURESPEED I/O Differential Electrical Characteristics (LVDS) table.
		Multiple	Removed references to HyperTransport throughout the data sheet.
January 2010	02.3	Introduction	Updated per PCN #01A-10 (ceramic fcBGA conversion to organic fcBGA for the 1152-ball and 1704-ball fcBGA packages) and PCN #02A-10 (1020-ball organic fcBGA conversion to 1020-ball organic fcBGA revision 2 package).
		Ordering Information	